

# Product Change Notification - GBNG-28LZAS041

#### Date:

27 Jun 2019

**Product Category:** 

8-bit Microcontrollers

#### Affected CPNs:

#### 7

# Notification subject:

CCB 3772 Final Notice: Qualification of MTAI as an additional assembly site for selected products of 290K wafer technology available in 48L TQFP (7x7x1.0mm) package using gold (Au) bond wire. **Notification text:** 

**PCN Status:** 

Final notification

PCN Type:

Manufacturing Change

# Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

# **Description of Change:**

Qualification of MTAI as an additional assembly site for selected products of 290K wafer technology available in 48L TQFP (7x7x1.0mm) package using gold (Au) bond wire..

# Pre Change:

Assembled at ANAP assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, 3230 die attach, G631HQ molding compound, C194 lead frame material with 197 x 197 mils lead frame paddle size.

# Post Change:

Assembled at ANAP assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, 3230 die attach, G631HQ molding compound, C194 lead frame material with 197 x 197 mils lead frame paddle size or assembled at MTAI assembly site using gold (Au) bond wire, 3280 die attach, G700HA mold compound, C7025 lead frame material with 200 x 200 mils lead frame paddle size.

	Pre Change	Post Change					
Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Microchip Technolog Thailand (HQ) / MTA				
Wire material	CuPdAu	CuPdAu	Au				
Die attach material	3230	3230	3280				
Molding compound material	G631HQ	G631HQ	G700HA				
Lead frame material	C194	C194	C7025				
Lead frame paddle size	197 x 197 mils	197 x 197 mils	200 x 200 mils				

## Pre and Post Change Summary:

Impacts to Data Sheet: None Change Impact: None



#### **Reason for Change:**

To improve productivity by qualifying MTAI as an additional assembly site.

**Change Implementation Status:** 

In Progress

## Estimated First Ship Date:

July 27, 2019 (date code: 1930)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

## Time Table Summary:

	June 2019				July 2019				
Workweek	23	24	25	26	27	28	29	30	31
Initial PCN Issue Date	Х								
Qual Report Availability				Х					
Final PCN Issue Date				Х					
Estimated Implementation Date								Х	

# Method to Identify Change:

Traceability code

**Qualification Report:** 

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report **Revision History**:

June 03, 2019: Issued initial notification.

**June 27, 2019:** Issued final notification. Attached the qualification report. Provided the estimated first ship date to be on July 27, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachment(s):

PCN\_GBNG-28LZAS041\_Qual\_Report.doc.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. GBNG-28LZAS041 - CCB 3772 Final Notice: Qualification of MTAI as an additional assembly site for selected products of 290K wafer technology available in 48L TQFP (7x7x1.0mm) package using gold (Au) bond wire.

Affected Catalog Part Numbers (CPN)

PIC16F15385-E/PT PIC16F15385-I/PT PIC16F15385T-I/PT PIC16F15386-E/PT PIC16F15386-I/PT PIC16F15386T-I/PT PIC16F19185-E/PT PIC16F19185-I/PT PIC16F19185T-I/PT PIC16F19186-E/PT PIC16F19186-I/PT PIC16F19186T-I/PT PIC16LF15385-E/PT PIC16LF15385-I/PT PIC16LF15385T-I/PT PIC16LF15386-E/PT PIC16LF15386-I/PT PIC16LF15386T-I/PT PIC16LF19185-E/PT PIC16LF19185-I/PT PIC16LF19185T-I/PT PIC16LF19186-E/PT PIC16LF19186-I/PT PIC16LF19186-I/PTC01 PIC16LF19186T-I/PT PIC16LF19186T-I/PTC01 PIC18F55K42-E/PT PIC18F55K42-I/PT PIC18F55K42T-I/PT PIC18F56K42-E/PT PIC18F56K42-I/PT PIC18F56K42T-I/PT PIC18F57K42-E/PT PIC18F57K42-I/PT PIC18F57K42T-I/PT PIC18LF55K42-E/PT PIC18LF55K42-I/PT PIC18LF55K42T-I/PT PIC18LF56K42-E/PT PIC18LF56K42-I/PT PIC18LF56K42T-I/PT PIC18LF57K42-E/PT PIC18LF57K42-I/PT PIC18LF57K42T-I/PT